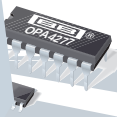
Jameco Part Number 905643



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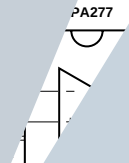
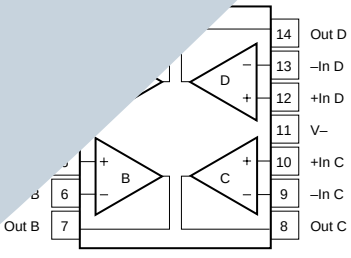
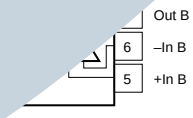
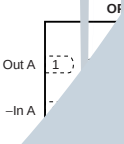




14-Pin DIP, SO-14



8-Pin DIP, SO-8



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ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage	36V
Input Voltage	(V–) –0.7V to (V+) +0.7V
Output Short-Circuit(2)	Continuous
Operating Temperature	–55°C to +125°C
Storage Temperature	–55°C to +125°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C
ESD Rating (Human Body Model)	2000V
(Machine Model)	100V

NOTE: (1) Stresses above these rating may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. (2) Short-circuit to ground, one amplifier per package.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

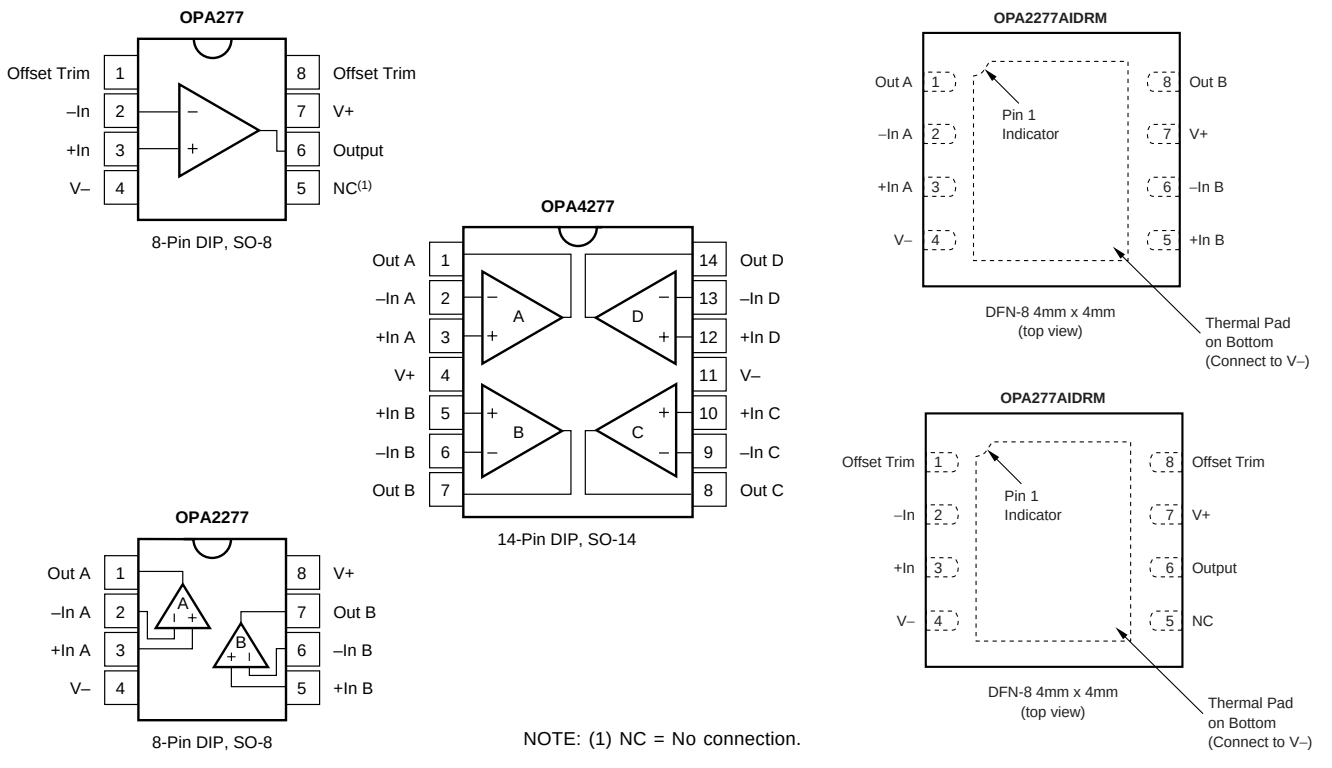
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	OFFSET VOLTAGE max, μV	OFFSET VOLTAGE DRIFT max, μV/°C	PACKAGE-LEAD
Single			
OPA277PA	±50	±1	DIP-8
OPA277P	±20	±0.15	DIP-8
OPA277UA	±50	±1	SO-8 Surface Mount
OPA277U	±20	±0.15	SO-8 Surface Mount
OPA277AIDRM	±100	±1	DFN-8 (4mm x 4mm)
Dual			
OPA2277PA	±50	±1	DIP-8
OPA2277P	±25	±0.25	DIP-8
OPA2277UA	±50	±1	SO-8 Surface Mount
OPA2277U	±25	±0.25	SO-8 Surface Mount
OPA2277AIDRM	±100	±1	DFN-8 (4mm x 4mm)
Quad			
OPA4277PA	±50	±1	DIP-14
OPA4277UA	±50	±1	SO-14 Surface Mount

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet or visit the TI web site at www.ti.com.

PIN DESCRIPTIONS



NOTE: (1) NC = No connection.

ELECTRICAL CHARACTERISTICS: V_S =

ELECTRICAL CHARACTERISTICS: V_S = ±5V to V_S = ±15V (CONT)

At T_A = +25°C, and R_L = 2kΩ, unless otherwise noted.
Boldface limits apply over the specified temperature range, –40°C to +85°C.

PARAMETER		CONDITION	OPA277P, U OPA2277P, U			OPA277PA, UA OPA2277PA, UA OPA4277PA, UA			OPA277AIDRM, OPA2277AIDRM			UNITS
			MIN	TYP[1]	MAX	MIN	TYP[1]	MAX	MIN	TYP[1]	MAX	
OUTPUT												
Voltage Output	V_O	R_L = 10kΩ	(V–) +0.5		(V+) –1.2	*		*	*		*	V
T_A = –40°C to +85°C		R_L = 10kΩ	**(V–) +0.5**		**(V+) –1.2**	*		*	*		*	**V**
		R_L = 2kΩ	(V–) +1.5		(V+) –1.5	*		*	*		*	V
T_A = –40°C to +85°C		R_L = 2kΩ	**(V–) +1.5**		**(V+) –1.5**	*		*	*		*	**V**
Short-Circuit Current	I_{SC}			±35			*			*		mA
Capacitive Load Drive	C_{LOAD}			See Typical Curve			*			*		
POWER SUPPLY												
Specified Voltage Range	V_S		±5		±15	*		*	*		*	V
Operating Voltage Range			±2		±18	*		*	*		*	V
Quiescent Current (per amplifier)	I_Q	I_O = 0		±790	±825		*	*		*	*	µA
T_A = –40°C to +85°C		I_O = 0			**±900**			*			*	**µA**
TEMPERATURE RANGE												
Specified Range			–40		+85	*		*	*		*	°C
Operating Range			–55		+125	*		*	*		*	°C
Storage Range			–55		+125	*		*	*		*	°C
Thermal Resistance	θ_{JA}											
SO-8 Surface-Mount				150			*					°C/W
DIP-8				100			*					°C/W
DIP-14				80			*					°C/W
SO-14 Surface-Mount				100			*					°C/W
DFN-8[2]										45		°C/W

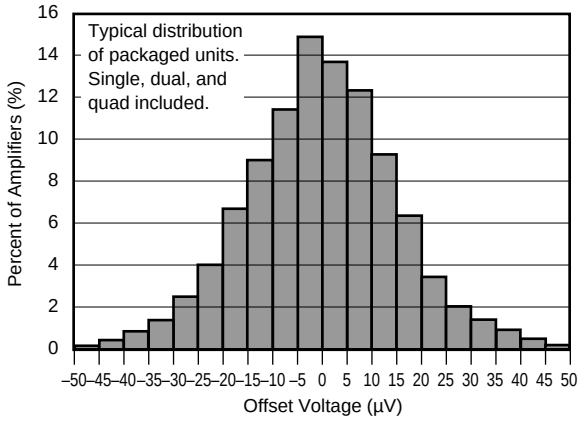
* Specifications same as OPA277P, U.

NOTES: (1) V_S = ±15V.
(2) Thermal pad soldered to printed circuit board (PCB).

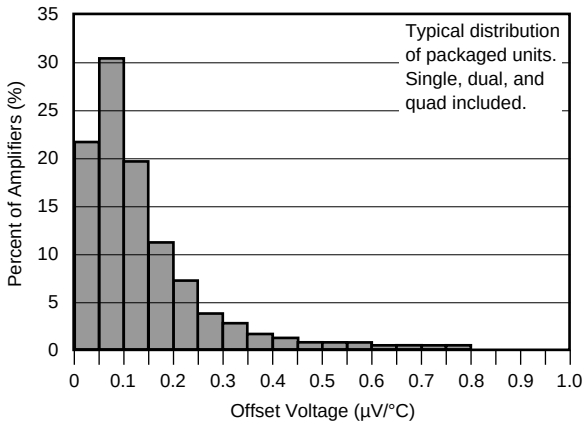
TYPICAL CHARACTERISTICS (CONT)

At T_A = +25°C, V_S = ±15V, and R_L = 2kΩ, unless otherwise noted.

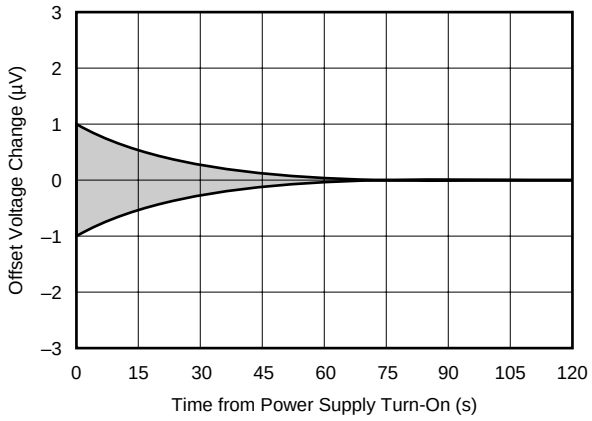
OFFSET VOLTAGE PRODUCTION DISTRIBUTION



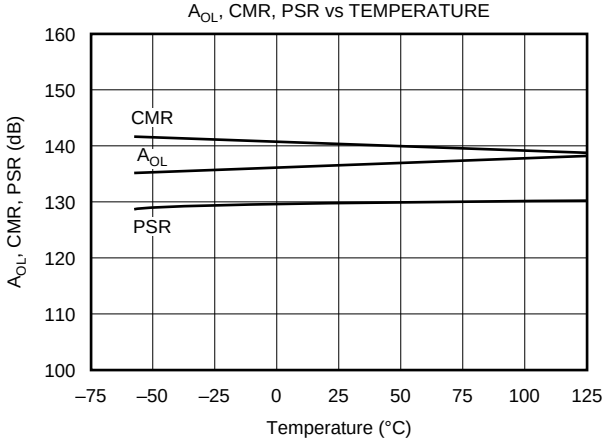
OFFSET VOLTAGE DRIFT PRODUCTION DISTRIBUTION



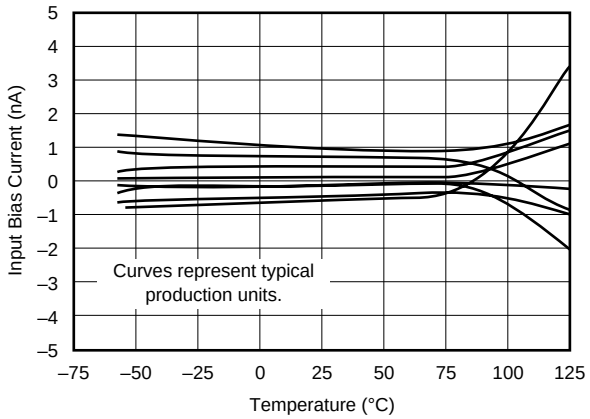
WARM-UP OFFSET VOLTAGE DRIFT



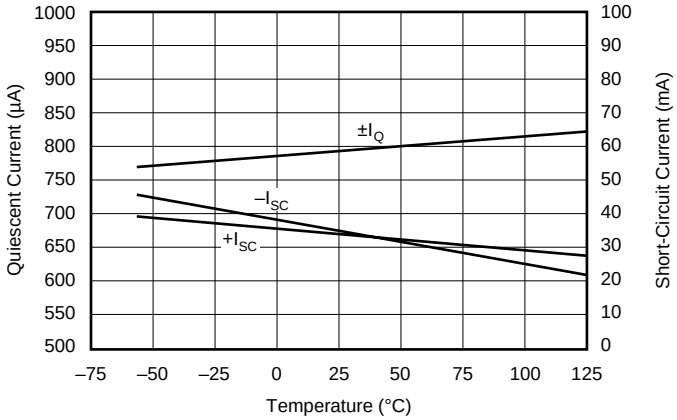
A_{OL}, CMR, PSR vs TEMPERATURE



INPUT BIAS CURRENT vs TEMPERATURE



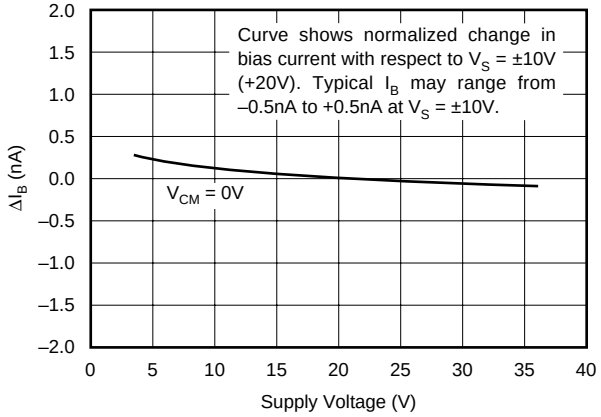
QUIESCENT CURRENT AND SHORT-CIRCUIT CURRENT vs TEMPERATURE



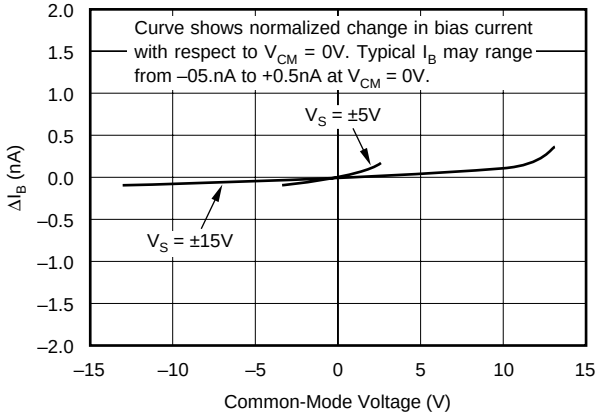
TYPICAL CHARACTERISTICS (CONT)

At T_A = +25°C, V_S = ±15V, and R_L = 2kΩ, unless otherwise noted.

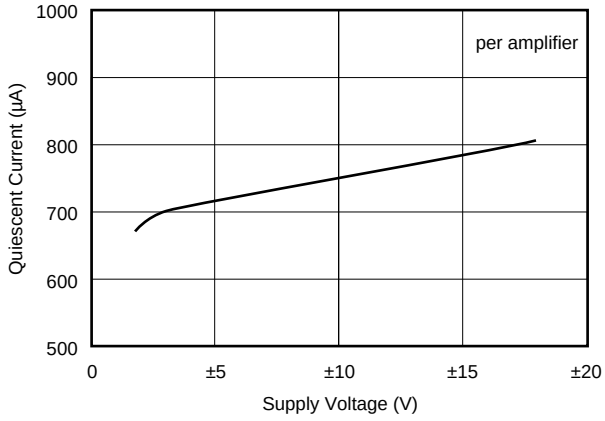
CHANGE IN INPUT BIAS CURRENT
vs POWER SUPPLY VOLTAGE



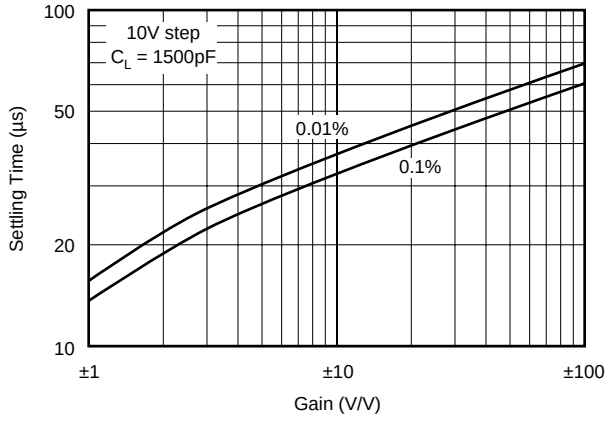
CHANGE IN INPUT BIAS CURRENT
vs COMMON-MODE VOLTAGE



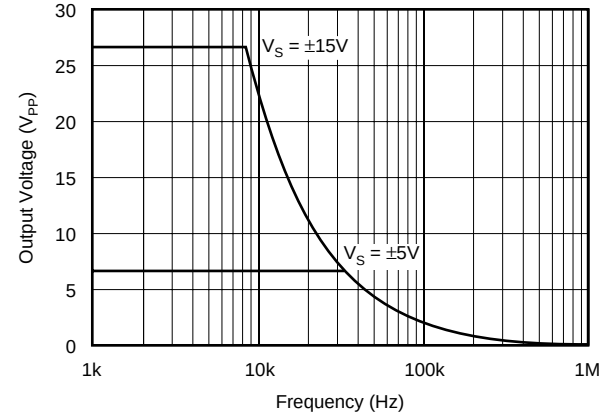
QUIESCENT CURRENT vs SUPPLY VOLTAGE



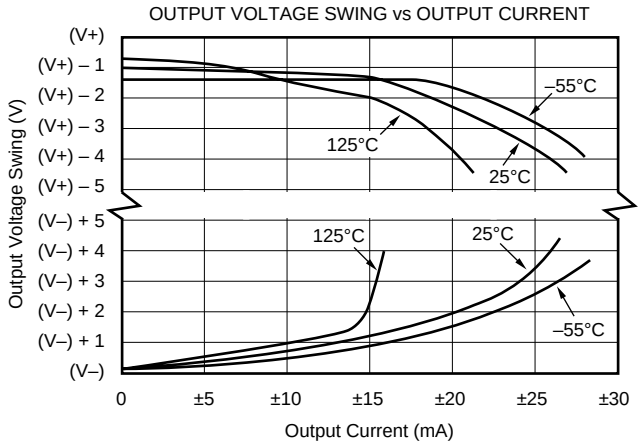
SETTLING TIME vs CLOSED-LOOP GAIN



MAXIMUM OUTPUT VOLTAGE
vs FREQUENCY



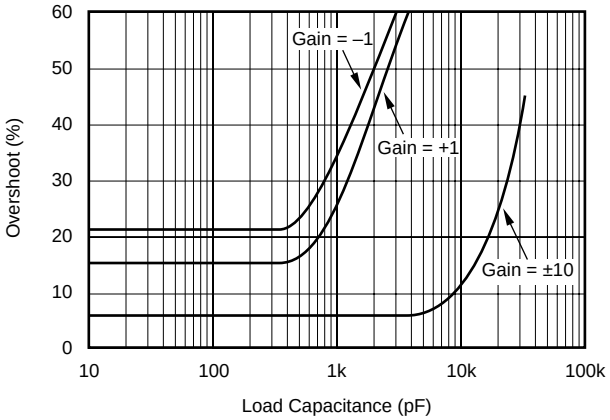
OUTPUT VOLTAGE SWING vs OUTPUT CURRENT



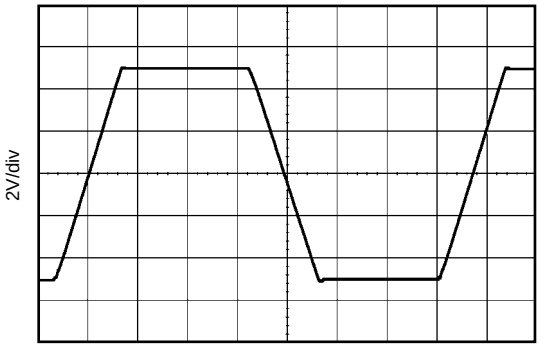
TYPICAL CHARACTERISTICS (CONT)

At T_A = +25°C, V_S = ±15V, and R_L = 2kΩ, unless otherwise noted.

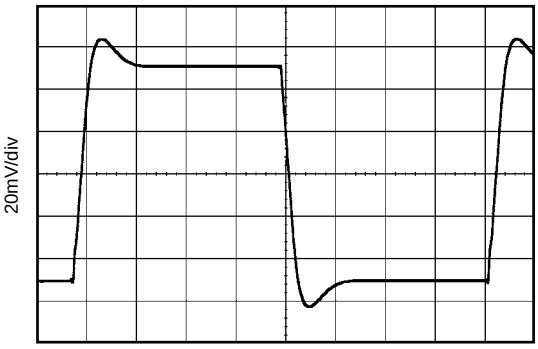
SMALL-SIGNAL OVERSHOOT
vs LOAD CAPACITANCE



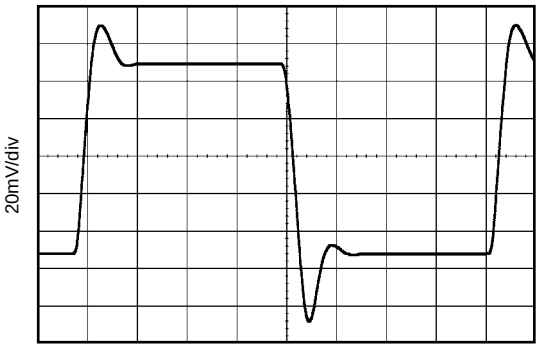
LARGE-SIGNAL STEP RESPONSE
G = +1, CL = 1500pF, V_S = +15V



SMALL-SIGNAL STEP RESPONSE
G = +1, C_L = 0, V_S = ±15V



SMALL-SIGNAL STEP RESPONSE
G = +1, C_L = 1500pF, V_S = ±15V



APPLICATIONS INFORMATION

The OPA277 series is unity-gain stable and free from unexpected output phase reversal, making it easy to use in a wide range of applications. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins. In most cases 0.1µF capacitors are adequate.

The OPA277 series has very low offset voltage and drift. To achieve highest performance, circuit layout and mechanical conditions should be optimized. Offset voltage and drift can be degraded by small thermoelectric potentials at the op amp inputs. Connections of dissimilar metals will generate thermal potential which can degrade the ultimate performance of the OPA277 series. These thermal potentials can be made to cancel by assuring that they are equal in both input terminals.

- Keep thermal mass of the connections made to the two input terminals similar.
- Locate heat sources as far as possible from the critical input circuitry.
- Shield op amp and input circuitry from air currents such as cooling fans.

OPERATING VOLTAGE

OPA277 series op amp operate from ±2V to ±18V supplies with excellent performance. Unlike most op amps which are specified at only one supply voltage, the OPA277 series is specified for real-world applications; a single limit applies over the ±5V to ±15V supply range. This allows a customer operating at V_S = ±10V to have the same assured performance as a customer using ±15V supplies. In addition, key parameters are assured over the specified temperature range, –40°C to +85°C. Most behavior remains unchanged through the full operating voltage range (±2V to ±18V). Parameters which vary significantly with operating voltage or temperature are shown in typical performance curves.

OFFSET VOLTAGE ADJUSTMENT

The OPA277 series is laser-trimmed for very low offset voltage and drift so most circuits will not require external adjustment. However, offset voltage trim connections are provided on pins 1 and 8. Offset voltage can be adjusted by connecting a potentiometer as shown in Figure 1. This adjustment should be used only to null the offset of the op amp. This adjustment should not be used to compensate for offsets created elsewhere in a system since this can introduce additional temperature drift.

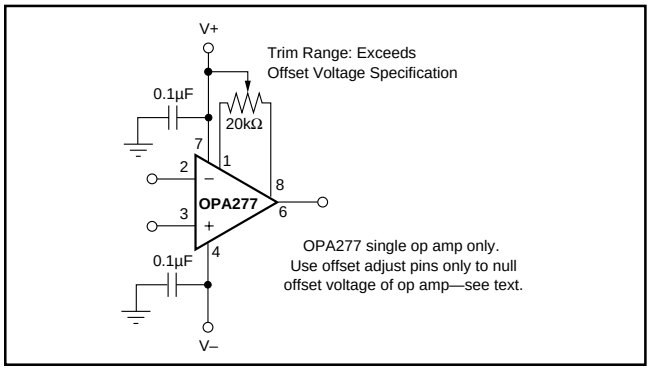


FIGURE 1. OPA277 Offset Voltage Trim Circuit.

INPUT PROTECTION

The inputs of the OPA277 series are protected with 1kΩ series input resistors and diode clamps. The inputs can withstand ±30V differential inputs without damage. The protection diodes will, of course, conduct current when the inputs are over-driven. This may disturb the slewing behavior of unity-gain follower applications, but will not damage the op amp.

INPUT BIAS CURRENT CANCELLATION

The input stage base current of the OPA277 series is internally compensated with an equal and opposite cancellation circuit. The resulting input bias current is the difference between the input stage base current and the cancellation current. This residual input bias current can be positive or negative.

When the bias current is canceled in this manner, the input bias current and input offset current are approximately the same magnitude. As a result, it is not necessary to use a bias current cancellation resistor as is often done with other op amps (Figure 2). A resistor added to cancel input bias current errors may actually increase offset voltage and noise.

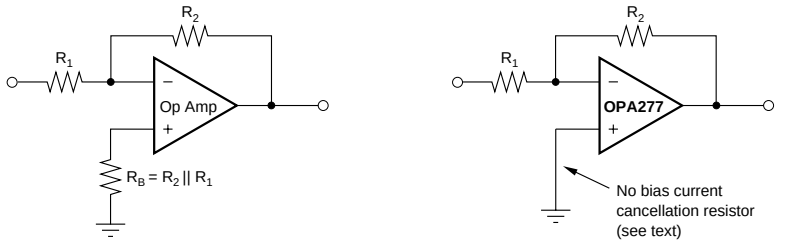


FIGURE 2. Input Bias Current Cancellation.

DFN PACKAGE

The OPA277 series uses the 8-lead DFN (also known as SON), which is a QFN package with contacts on only two sides of the package bottom. This leadless, near-chip-scale package maximizes board space and enhances thermal and electrical characteristics through an exposed pad.

DFN packages are physically small, have a smaller routing area, improved thermal performance, and improved electrical parasitics, with a pinout scheme that is consistent with other commonly-used packages, such as SO and MSOP. Additionally, the absence of external leads eliminates bent-lead issues.

The DFN package can be easily mounted using standard printed circuit board (PCB) assembly techniques. See Application Note, *QFN/SON PCB Attachment* (SLUA271) and Application Report, *Quad Flatpack No-Lead Logic Packages* (SCBA017), both available for download at www.ti.com.

The exposed leadframe die pad on the bottom of the package should be connected to V–.

LAYOUT GUIDELINES

The leadframe die pad should be soldered to a thermal pad on the PCB. Mechanical drawings located at the end of this data sheet list the physical dimensions for the package and pad.

Soldering the exposed pad significantly improves board-level reliability during temperature cycling, key push, package shear, and similar board-level tests. Even with applications that have low-power dissipation, the exposed pad **must** be soldered to the PCB to provide structural integrity and long-term reliability.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
OPA2277AIDRMR	ACTIVE	SON	DRM	8	3000	TBD	Call TI	Call TI
OPA2277AIDRMT	ACTIVE	SON	DRM	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA2277AIDRMTG4	ACTIVE	SON	DRM	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA2277P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2277PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2277PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2277PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2277U	ACTIVE	SOIC	D	8	100	TBD	CU NIPDAU	Level-3-220C-168 HR
OPA2277U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2277U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2277UA	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2277UA/2K5	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA2277UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2277UAE4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2277UAG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2277UG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA277AIDRMR	ACTIVE	SON	DRM	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA277AIDRMRG4	ACTIVE	SON	DRM	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA277AIDRMT	ACTIVE	SON	DRM	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA277AIDRMTG4	ACTIVE	SON	DRM	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA277P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA277PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA277PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA277PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA277U	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA277U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS &	CU NIPDAU	Level-3-260C-168 HR

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
						no Sb/Br)		
OPA277U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA277UA	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA277UA/2K5	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA277UA/2K5E4	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA277UAE4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA277UG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4277PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA4277UA	ACTIVE	SOIC	D	14	58	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4277UA/2K5	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA4277UA/2K5E4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA4277UAE4	ACTIVE	SOIC	D	14	58	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA4277UAG4	ACTIVE	SOIC	D	14	58	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

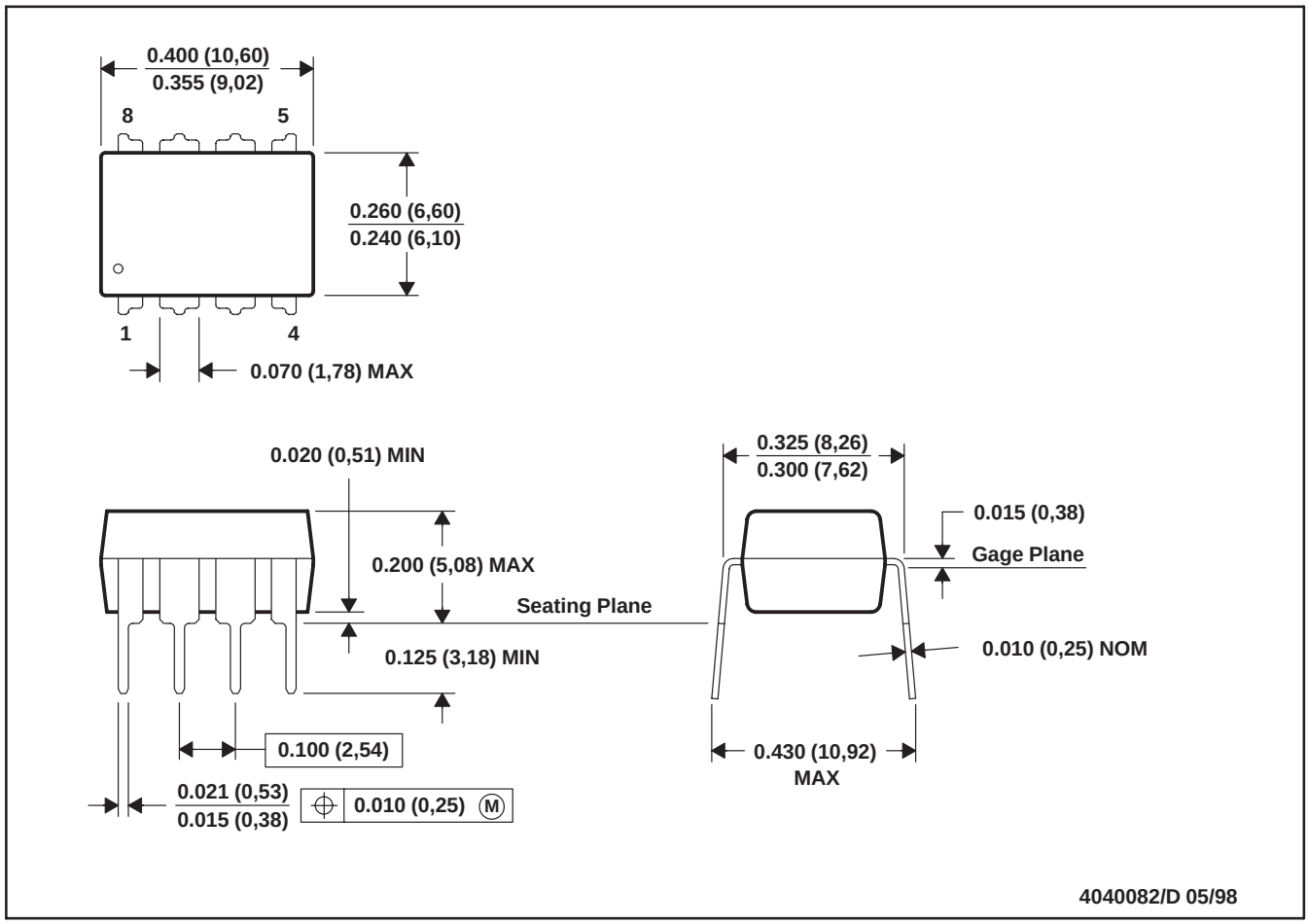
[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

MPDI001A – JANUARY 1995 – REVISED JUNE 1999

P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**



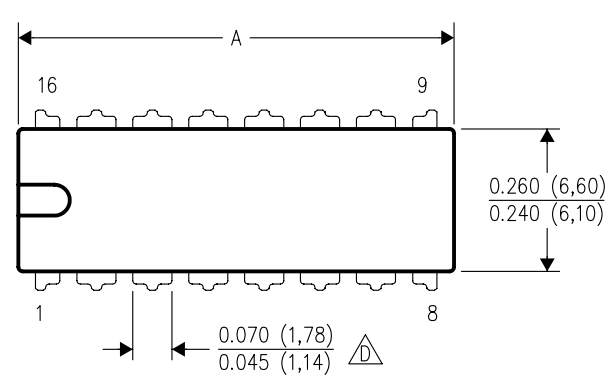
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

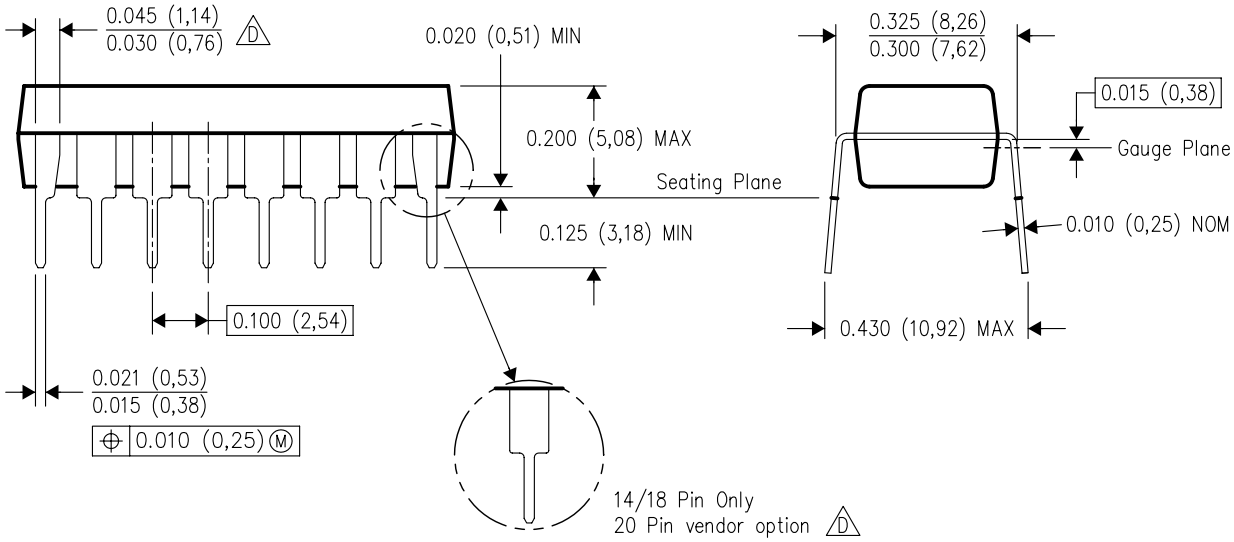
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

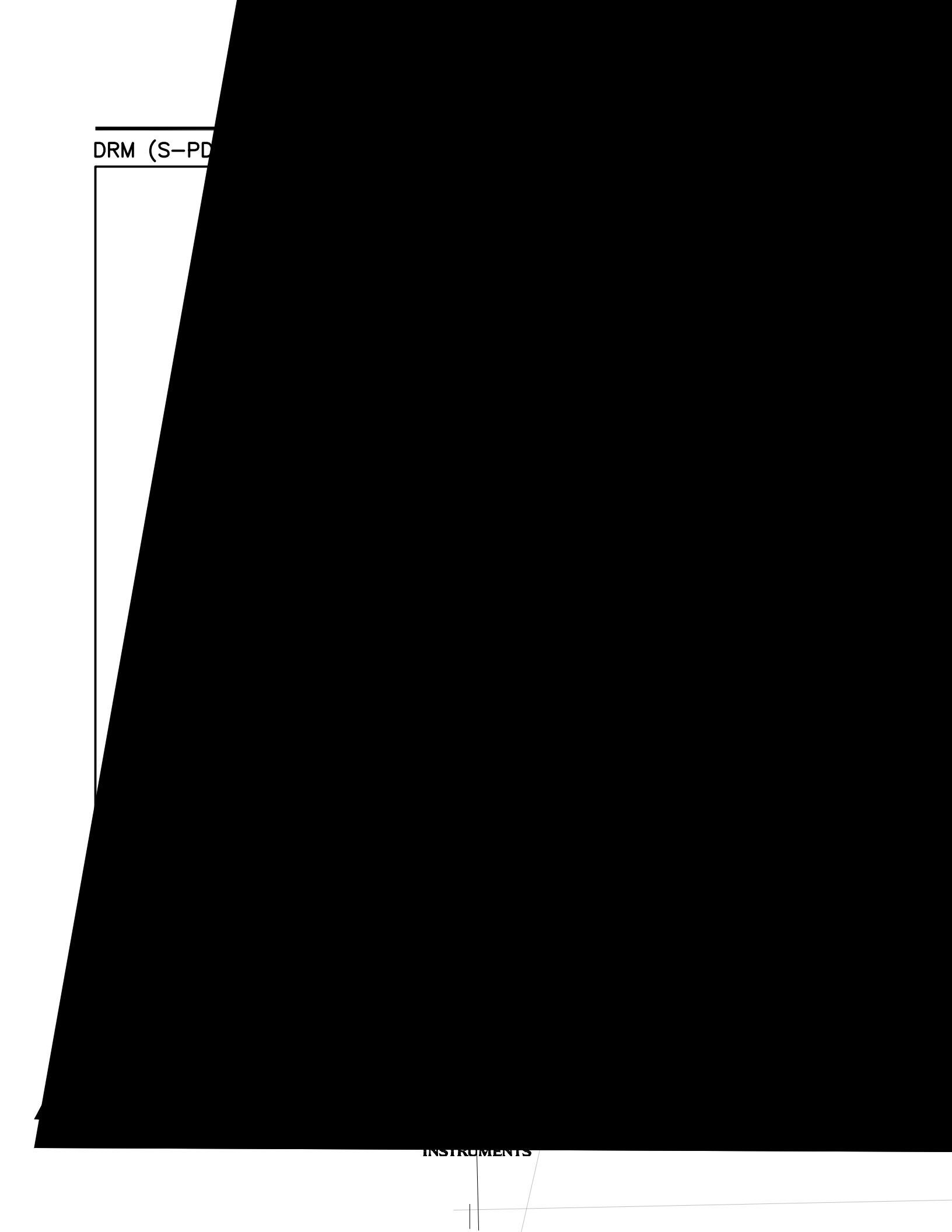


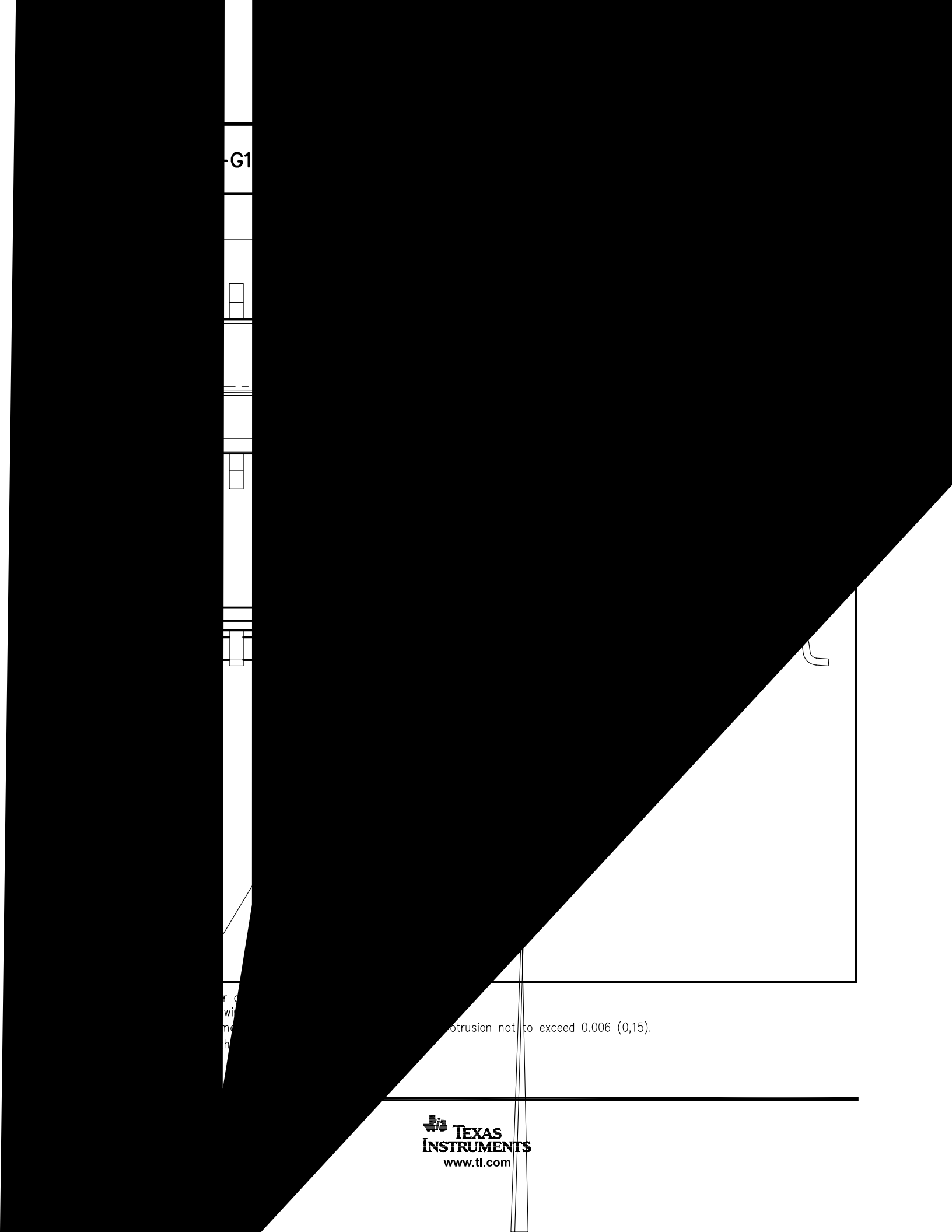
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

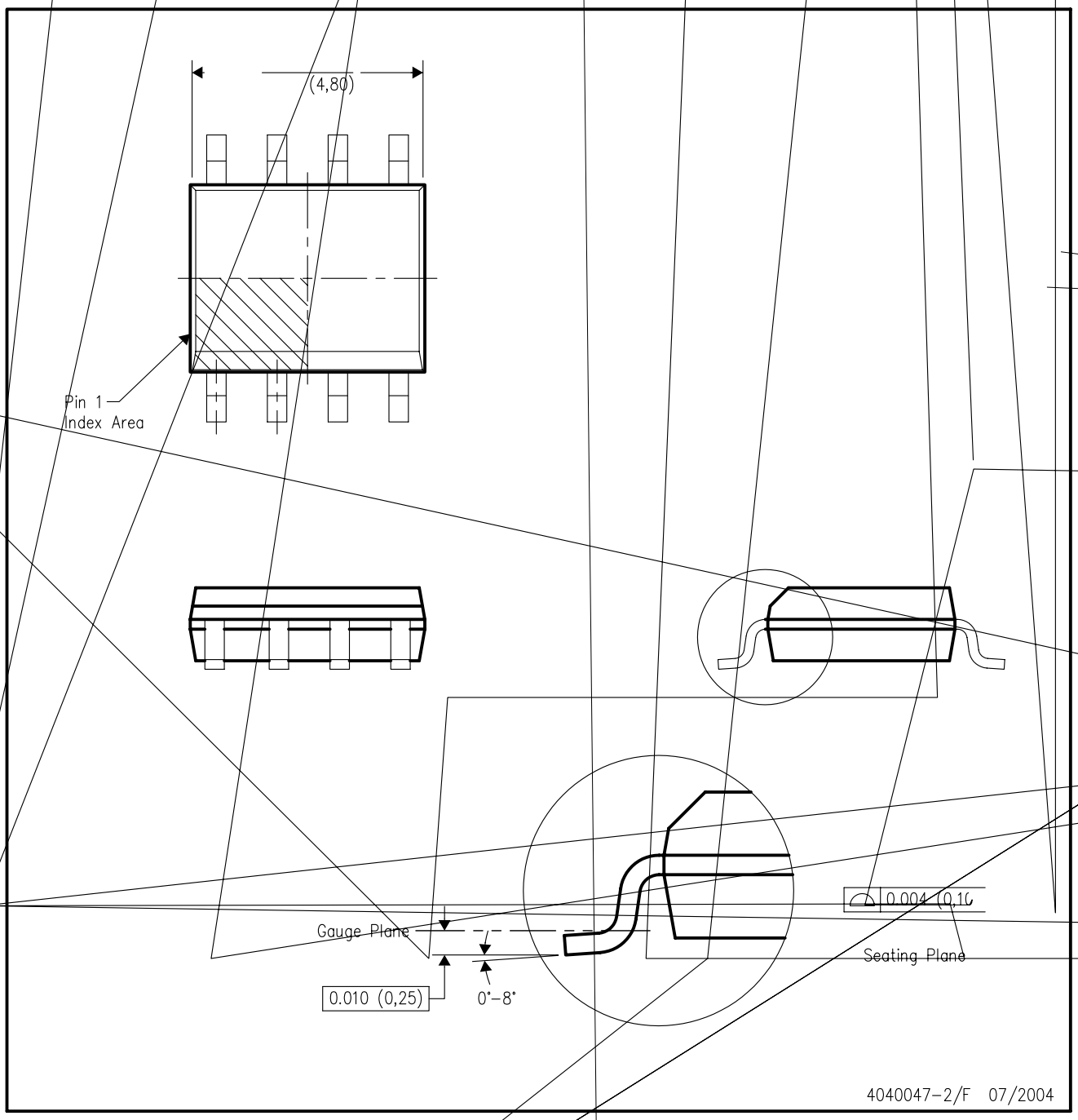
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.


DRM (S–PD
INSTRUMENTS



otrusion not to exceed 0.006 (0,15).

D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AA.

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